Microchip Technology - PIC16C716-20I/SS Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c716-20i-ss

TABLE 1-1: PIC16C712/716 PINOUT DESCRIPTION (CONTINUED)

Pin Name	PIC16C712/716 DIP, SOIC	PIC16C712/716 SSOP	Pin Type	Buffer Type	Description
					PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT	6	7			
RB0			I/O	TTL	Digital I/O
INT			I	ST	External Interrupt
RB1/T1OSO/T1CKI	7	8			
RB1			I/O	TTL	Digital I/O
T1OSO			O	—	Timer1 oscillator output. Connects to crystal in oscillator mode.
T1CKI			I	ST	Timer1 external clock input.
RB2/T1OSI	8	9			
RB2			I/O	TTL	Digital I/O
T1OSI			I	—	Timer1 oscillator input. Connects to crystal in oscillator mode.
RB3/CCP1	9	10			
RB3			I/O	TTL	Digital I/O
CCP1			I/O	ST	Capture1 input, Compare1 output, PWM1 output.
RB4	10	12	I/O	TTL	Digital I/O Interrupt on change pin.
RB5	11	12	I/O	TTL	Digital I/O Interrupt on change pin.
RB6	12	13	I/O	TTL	Digital I/O Interrupt on change pin.
			I	ST	ICSP programming clock.
RB7	13	14	I/O	TTL	Digital I/O Interrupt on change pin.
			I/O	ST	ICSP programming data.
VSS	5	5, 6	P	—	Ground reference for logic and I/O pins.
VDD	14	15, 16	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL-compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
OD = Open drain output
SM = SMBus compatible input. An external resistor is required if this pin is used as an output
NPU = N-channel pull-up PU = Weak internal pull-up
No-P diode = No P-diode to VDD AN = Analog input or output
I = input O = output
P = Power L = LCD Driver

NOTES:

2.2.2.3 INTCON Register

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts.

Note:	Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-6: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7: **GIE:** Global Interrupt Enable bit
1 = Enables all unmasked interrupts
0 = Disables all interrupts

bit 6: **PEIE**: Peripheral Interrupt Enable bit
1 = Enables all unmasked peripheral interrupts
0 = Disables all peripheral interrupts

bit 5: **T0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enables the TMR0 interrupt
0 = Disables the TMR0 interrupt

bit 4: **IINTE**: RB0/INT External Interrupt Enable bit
1 = Enables the RB0/INT external interrupt
0 = Disables the RB0/INT external interrupt

bit 3: **RBIE**: RB Port Change Interrupt Enable bit
1 = Enables the RB port change interrupt
0 = Disables the RB port change interrupt

bit 2: **T0IF**: TMR0 Overflow Interrupt Flag bit
1 = TMR0 register has overflowed (must be cleared in software)
0 = TMR0 register did not overflow

bit 1: **INTF**: RB0/INT External Interrupt Flag bit
1 = The RB0/INT external interrupt occurred (must be cleared in software)
0 = The RB0/INT external interrupt did not occur

bit 0: **RBIF**: RB Port Change Interrupt Flag bit
1 = At least one of the RB7:RB4 pins changed state (must be cleared in software)
0 = None of the RB7:RB4 pins have changed state

2.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 2-1: INDIRECT ADDRESSING

- Register file 05 contains the value 10h
- Register file 06 contains the value 0Ah
- Load the value 05 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 06)
- A read of the INDR register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although Status bits may be affected).

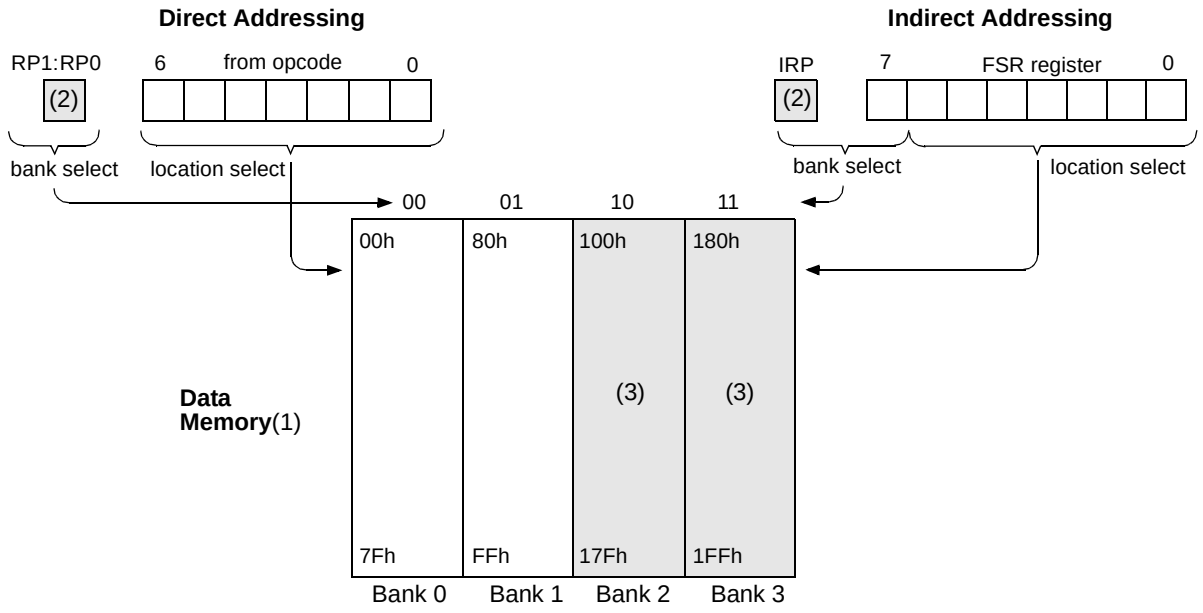
A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 2-2.

EXAMPLE 2-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

```
          MOVLW  0x20  ;initialize pointer
          MOVWF  FSR   ;  to RAM
NEXT      CLRF   INDF  ;clear INDF register
          INCF   FSR   ;inc pointer
          BTFSS  FSR,4 ;all done?
          GOTO   NEXT  ;NO, clear next
CONTINUE
          :            ;YES, continue
```

An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-10. However, IRP is not used in the PIC16C712/716.

FIGURE 2-10: DIRECT/INDIRECT ADDRESSING



Note 1: For register file map detail see Figure 2-3.

2: Maintain clear for upward compatibility with future products.

3: Not implemented.

FIGURE 3-1: BLOCK DIAGRAM OF RA3:RA0

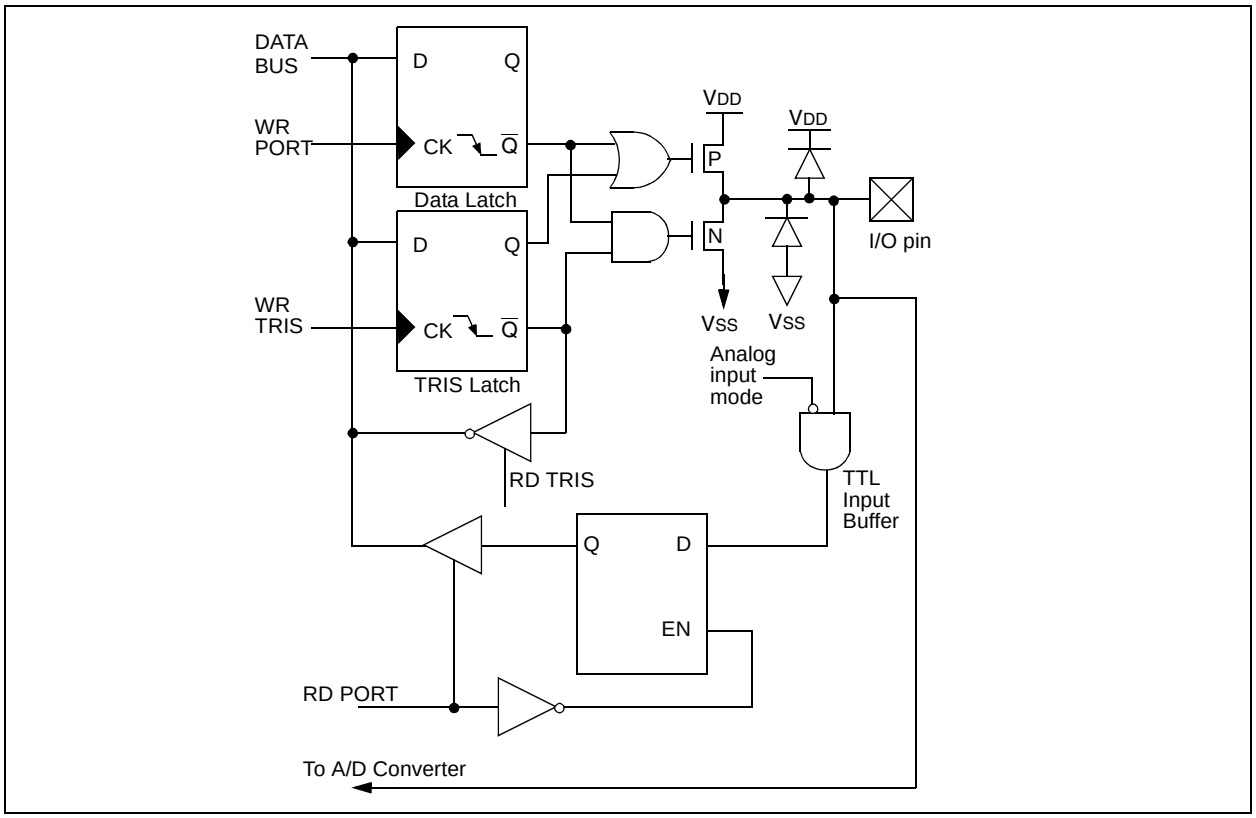
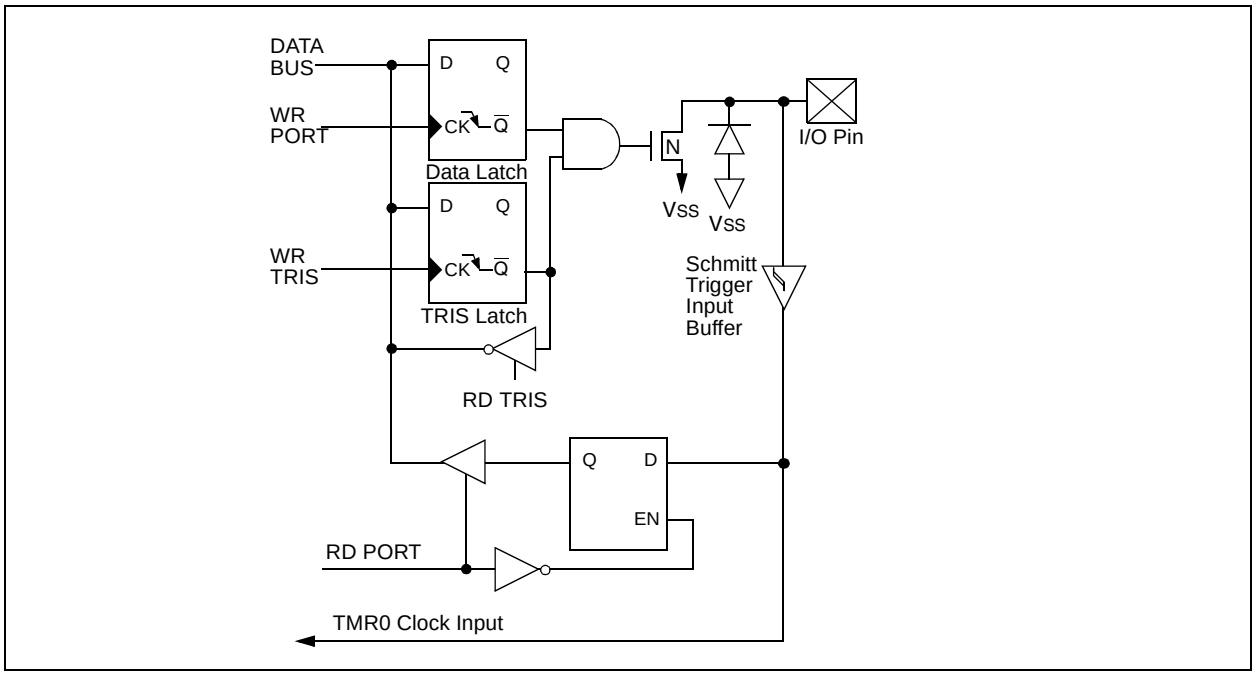


FIGURE 3-2: BLOCK DIAGRAM OF RA4/T0CKI PIN



PORTB pins RB3:RB1 are multiplexed with several peripheral functions (Table 3-3). PORTB pins RB3:RB0 have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTB pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modify-write instructions (`BSF, BCF, XORWF`) with TRISB as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

Four of PORTB's pins, RB7:RB4, have an interrupt-on-change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB7:RB4 pin configured as an output is excluded from the interrupt-on-change comparison). The input pins, RB7:RB4, are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

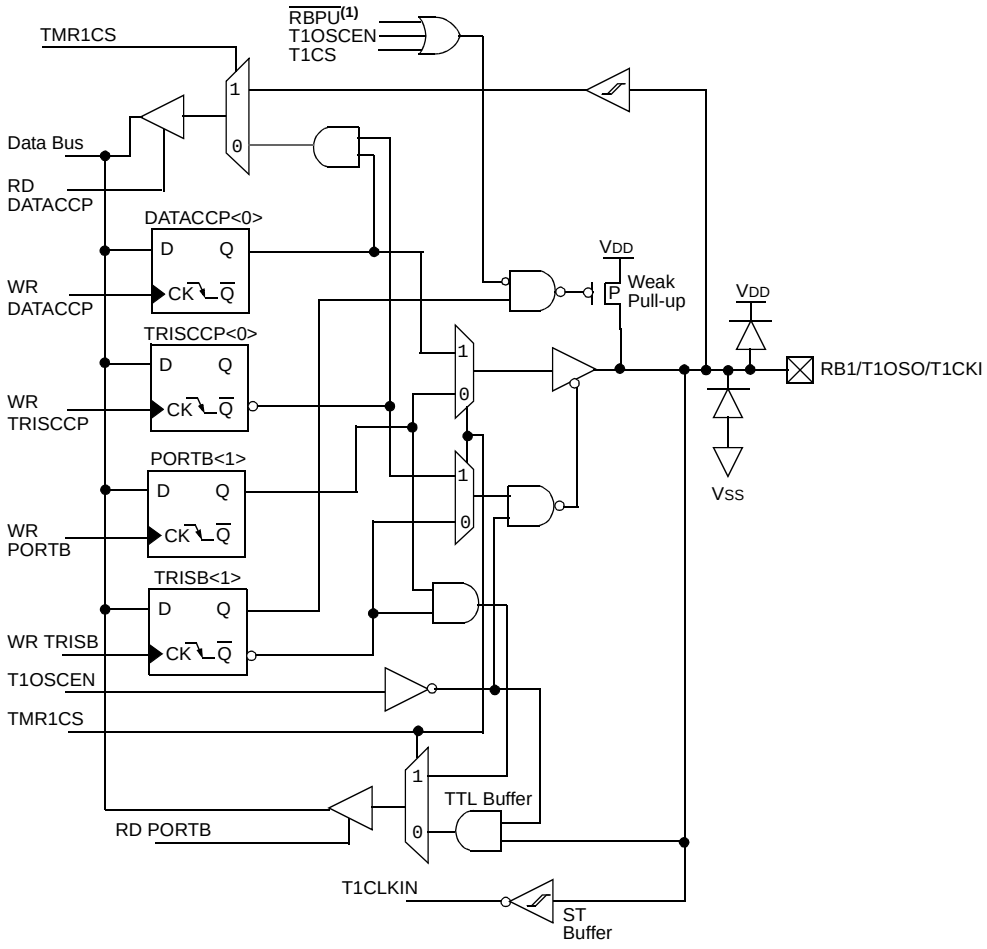
a) Any read or write of PORTB will end the mismatch condition.

b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

FIGURE 3-4: BLOCK DIAGRAM OF RB1/T1OSO/T1CKI PIN



Note 1: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the RBPU bit (OPTION_REG<7>).

5.0 TIMER1 MODULE

The Timer1 module timer/counter has the following features:

- 16-bit timer/counter
  (Two 8-bit registers; TMR1H and TMR1L)
- Readable and writable (Both registers)
- Internal or external clock select
- Interrupt on overflow from FFFFh to 0000h
- Reset from CCP module trigger

Timer1 has a control register, shown in Figure 5-1. Timer1 can be enabled/disabled by setting/clearing control bit TMR1ON (T1CON<0>).

Figure 5-2 is a simplified block diagram of the Timer1 module.

Additional information on timer modules is available in the PIC® Mid-Range Reference Manual, (DS33023).

5.1 Timer1 Operation

Timer1 can operate in one of these modes:

- As a timer
- As a synchronous counter
- As an asynchronous counter

The operating mode is determined by the clock select bit, TMR1CS (T1CON<1>).

In timer mode, Timer1 increments every instruction cycle. In counter mode, it increments on every rising edge of the external clock input.

When the Timer1 oscillator is enabled (T1OSCEN is set), the RB2/T1OSI and RB1/T1OSO/T1CKI pins become inputs. That is, the TRISB<2:1> value is ignored.

Timer1 also has an internal “Reset input”. This Reset can be generated by the CCP module (see **Section 7.0 “Capture/Compare/PWM (CCP) Module(s)”**).

FIGURE 5-1: T1CON: TIMER1 CONTROL REGISTER (ADDRESS 10h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR Reset

bit 7-6: **Unimplemented:** Read as ‘0’

bit 5-4: **T1CKPS1:T1CKPS0**: Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3: **T1OSCEN**: Timer1 Oscillator Enable Control bit
1 = Oscillator is enabled
0 = Oscillator is shut off
Note: The oscillator inverter and feedback resistor are turned off to eliminate power drain

bit 2: **$\overline{\text{T1SYNC}}$**: Timer1 External Clock Input Synchronization Control bit

TMR1CS = 1
1 = Do not synchronize external clock input
0 = Synchronize external clock input

TMR1CS = 0
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1: **TMR1CS**: Timer1 Clock Source Select bit
1 = External clock from pin RB1/T1OSO/T1CKI (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0: **TMR1ON**: Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

NOTES:

7.4 CCP1 Module and PORTB Operation

When the CCP module is disabled, PORTB<3> operates as a normal I/O pin. When the CCP module is enabled, PORTB<3> operation is affected. Multiplexing details of the CCP1 module are shown on PORTB<3>, refer to Figure 3.6.

Table 7-5 below shows the effects of the CCP module operation on PORTB<3>

TABLE 7-5: CCP1 MODULE AND PORTB OPERATION

CCP1 Module Mode	Control Bits	CCP1 Module Operation	PORTB<3> Operation
Off	CCP1CON = --xx 0000	Off	PORTB<3> functions as normal I/O.
Capture	CCP1CON = --xx 01xx TRISCCP = ---- -1-x	The CCP1 module will capture an event on the RB3/CCP1 pin which is driven by an external circuit. The DCCP bit can read the signal on the RB3/CCP1 pin.	PORTB<3> always reads '0' when configured as input. If PORTB<3> is configured as output, reading PORTB<3> will read the data latch. Writing to PORTB<3> will always store the result in the data latch, but it does not drive the RB3/CCP1 pin.
	CCP1CON = --xx 01xx TRISCCP = ---- -0-x	The CCP1 module will capture an event on the RB3/CCP1 pin which is driven by the DCCP bit. The DCCP bit can read the signal on the RB3/CCP1 pin.	
Compare	CCP1CON = --xx 10xx TRISCCP = ---- -0-x	The CCP1 module produces an output on the RB3/CCP1 pin when a compare event occurs. The DCCP bit can read the signal on the RB3/CCP1 pin.	
PWM	CCP1CON = --xx 11xx TRISCCP = ---- -0-x	The CCP1 module produces the PWM signal on the RB3/CCP1 pin. The DCCP bit can read the signal on the RB3/CCP1 pin.	

8.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has four inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (V_{DD}) or the voltage level on the RA3/AN3/V_{REF} pin.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

Additional information on the A/D module is available in the PIC® Mid-Range Reference Manual, (DS33023).

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The ADCON0 register, shown in Figure 8-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 8-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

FIGURE 8-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	$\overline{\text{ADON}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-6: **ADCS1:ADCS0:** A/D Conversion Clock Select bits
00 = F_{OSC}/2
01 = F_{OSC}/8
10 = F_{OSC}/32
11 = F_{RC} (clock derived from the internal ADC RC oscillator)

bit 5-3: **CHS2:CHS0**: Analog Channel Select bits
000 = channel 0, (RA0/AN0)
001 = channel 1, (RA1/AN1)
010 = channel 2, (RA2/AN2)
011 = channel 3, (RA3/AN3)
1xx = reserved, do not use

bit 2: **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

If ADON = 1
1 = A/D conversion in progress (setting this bit starts the A/D conversion)
0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: **Unimplemented**: Read as '0'

bit 0: **ADON**: A/D On bit
1 = A/D converter module is operating
0 = A/D converter module is shutoff and consumes no operating current

FIGURE 8-2: ADCON1 REGISTER (ADDRESS 9Fh)

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	PCFG2	PCFG1	PCFG0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-3: **Unimplemented:** Read as '0'

bit 2-0: **PCFG2:PCFG0**: A/D Port Configuration Control bits

PCFG2:PCFG0	RA0	RA1	RA2	RA3	VREF
0x0	A	A	A	A	VDD
0x1	A	A	A	VREF	RA3
100	A	A	D	A	VDD
101	A	A	D	VREF	RA3
11x	D	D	D	D	VDD

A = Analog input

D = Digital I/O

8.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the Charge Holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ.** After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, TACQ, see the PIC® Mid-Range Reference Manual, (DS33023). This equation calculates the acquisition time to within 1/2 LSb error (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

Note:	When the conversion is started, the holding capacitor is disconnected from the input pin.

FIGURE 8-4: ANALOG INPUT MODEL

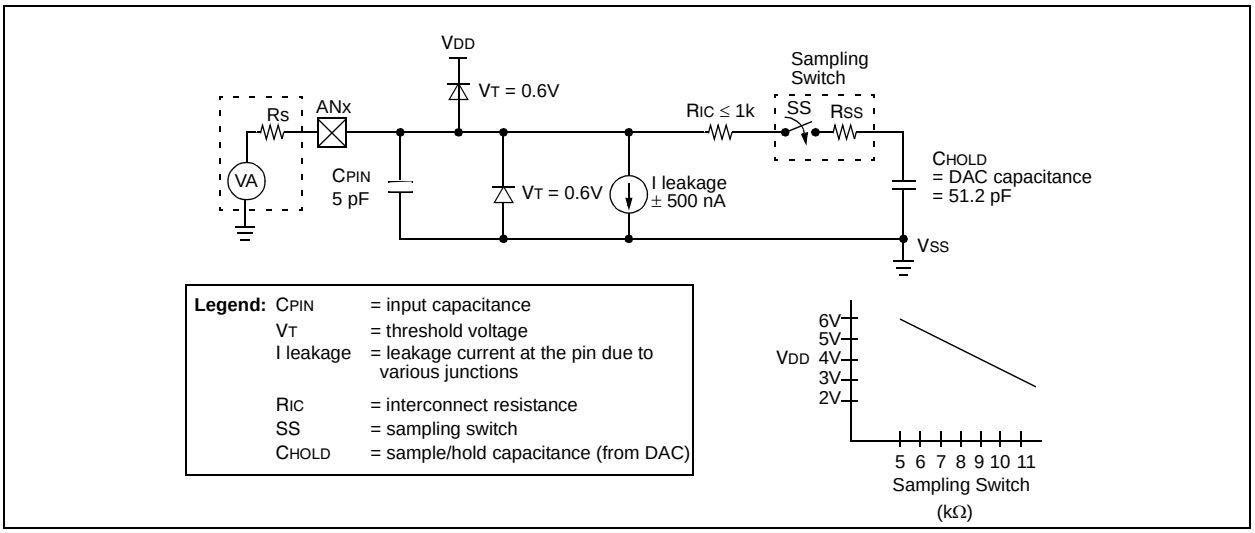


FIGURE 9-11: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ TIED TO V_{DD})

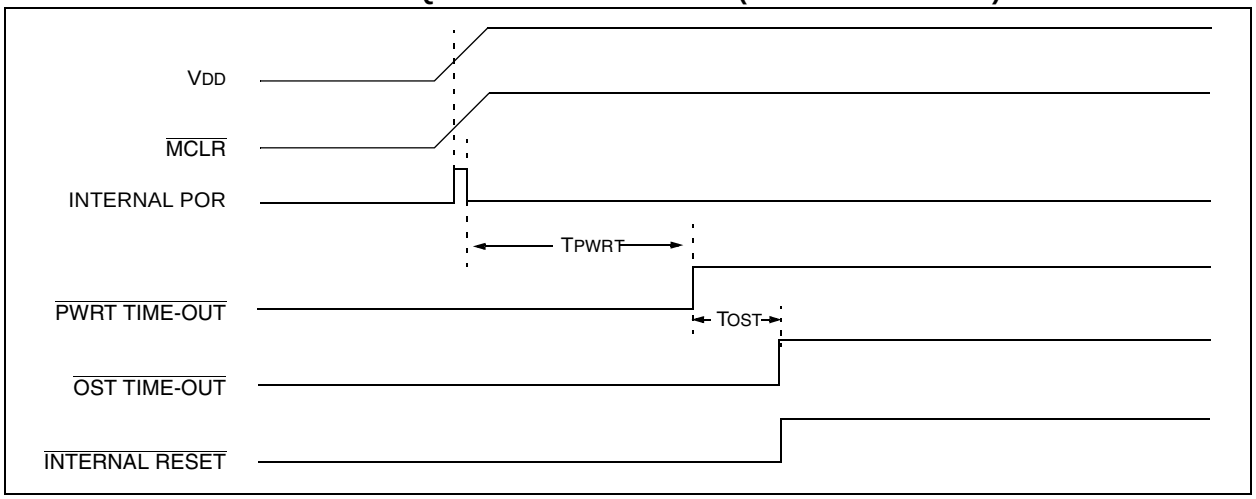


FIGURE 9-12: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 1

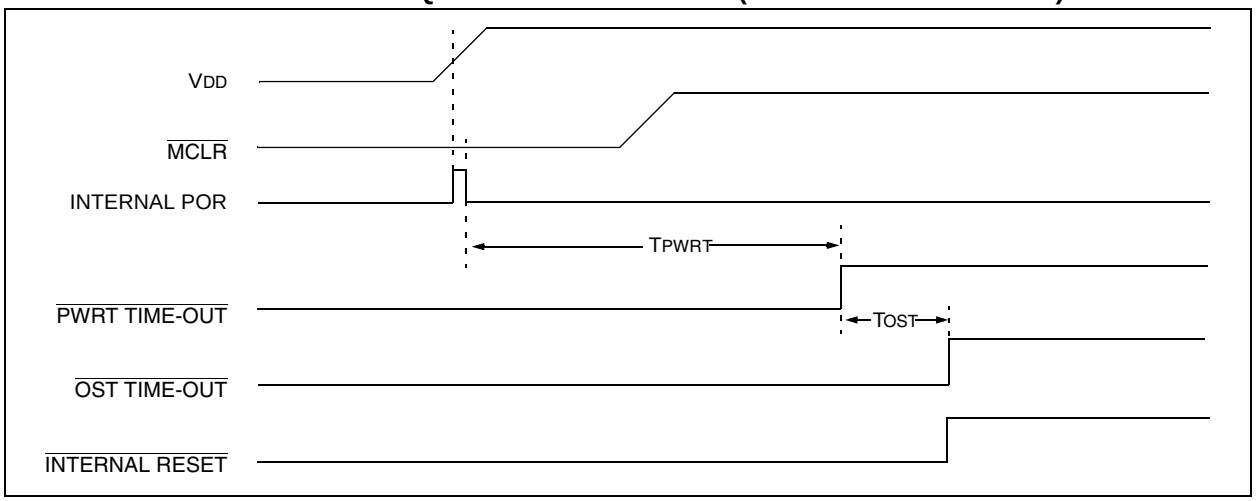
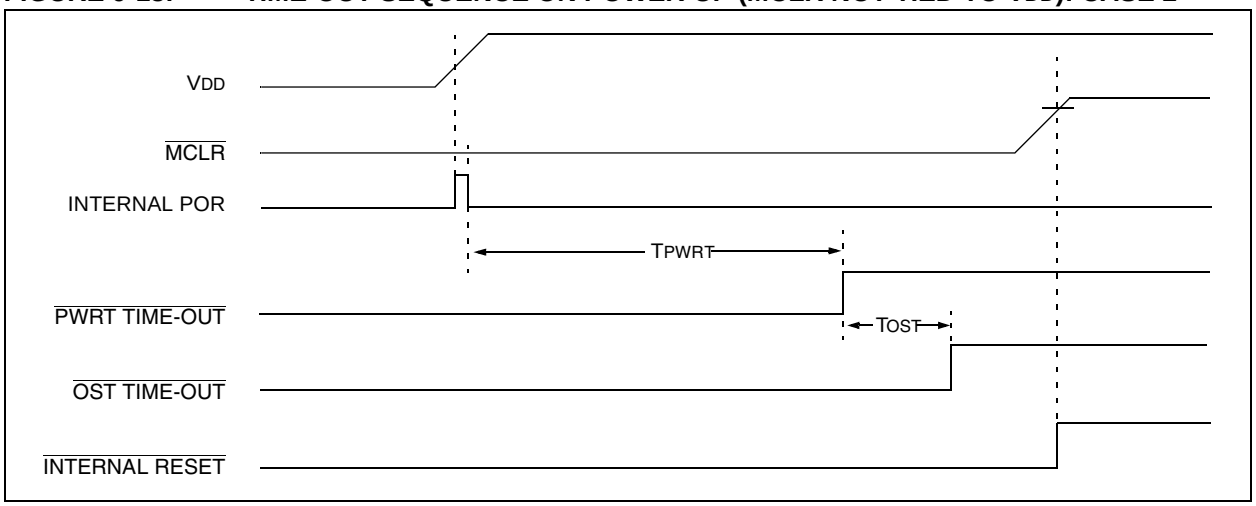


FIGURE 9-13: TIME-OUT SEQUENCE ON POWER-UP ($\overline{MCLR}$ NOT TIED TO V_{DD}): CASE 2



11.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C18 and MPLAB C30 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB ASM30 Assembler/Linker/Library
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - MPLAB ICE 4000 In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD 2
- Device Programmers
  - PICSTART® Plus Development Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration and Development Boards and Evaluation Kits

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Visual device initializer for easy register initialization
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as HI-TECH Software C Compilers and IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (assembly or C)
  - Mixed assembly and C
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

11.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

11.12 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart® battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) and the latest *"Product Selector Guide"* (DS00148) for the complete list of demonstration, development and evaluation kits.

12.1 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.0	—	5.5	V	XT, RC and LP osc mode
D001A			4.5	—	5.5	V	HS osc mode
			VBOR*	—	5.5	V	BOR enabled(7)
D002*	VDR	**RAM Data Retention Voltage(1)**	—	1.5	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	PWRT enabled ($\overline{\text{PWRTE}}$ bit clear)
D004A*			TBD	—	—		PWRT disabled ($\overline{\text{PWRTE}}$ bit set) See section on Power-on Reset for details
D005	VBOR	**Brown-out Reset** voltage trip point	3.65	—	4.35	V	BODEN bit set
D010	IDD	**Supply Current(2,5)**	—	0.8	2.5	mA	FOSC = 4 MHz, VDD = 4.0V
D013			—	4.0	8.0	mA	FOSC = 20 MHz, VDD = 4.0V
D020	IPD	**Power-down Current(3,5)**	—	10.5	42	µA	VDD = 4.0V, WDT enabled,-40°C to +85°C
			—	1.5	16	µA	VDD = 4.0V, WDT disabled, 0°C to +70°C
D021			—	1.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +85°C
D021B			—	2.5	19	µA	VDD = 4.0V, WDT disabled,-40°C to +125°C
		Module Differential Current(6)					
D022*	ΔIWDT	Watchdog Timer	—	6.0	20	µA	WDTE bit set, VDD = 4.0V
D022A*	ΔIBOR	Brown-out Reset	—	TBD	200	µA	BODEN bit set, VDD = 5.0V
1A	FOSC	LP Oscillator Operating Frequency	0	—	200	KHz	All temperatures
		RC Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		XT Oscillator Operating Frequency	0	—	4	MHz	All temperatures
		HS Oscillator Operating Frequency	0	—	20	MHz	All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in DC spec **Section 12.1 "DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)"** and **Section 12.2 "DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)"**					
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Output Low Voltage					
D080	VOL	I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C
			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C
D083		OSC2/CLKOUT (RC Osc mode)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
			—	—	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C
		Output High Voltage					
D090	VOH	I/O ports **(Note 3)**	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C
			VDD-0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C
D092		OSC2/CLKOUT (RC Osc mode)	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
			VDD-0.7	—	—	V	IOH = -1.0 mA, VDD = 4.5V, -40°C to +125°C
D150*	VOD	**Open-Drain High Voltage**	—	—	8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	CIO	All I/O pins and OSC2 (in RC mode)	—	—	50	pF	

* These parameters are characterized but not tested.

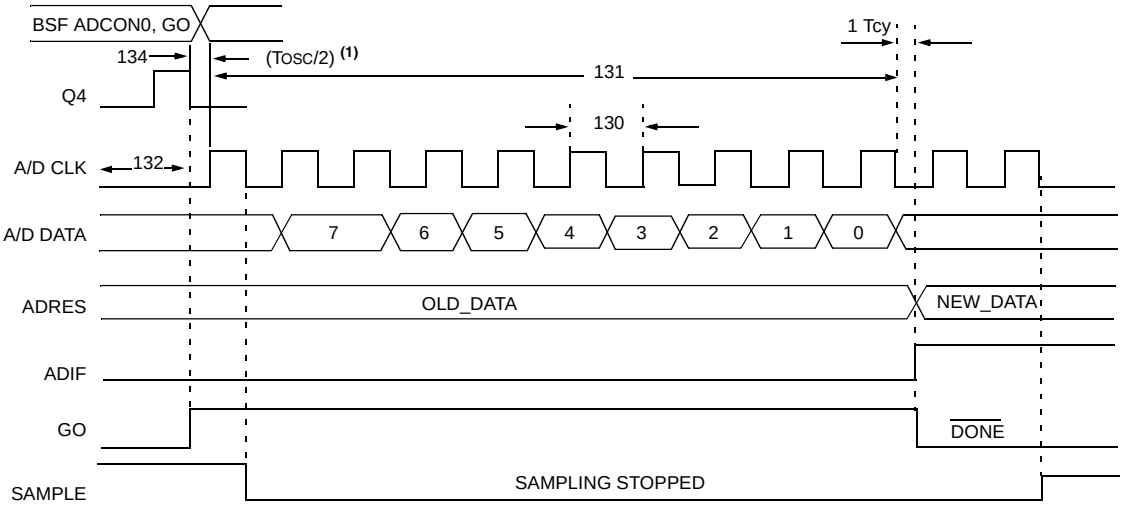
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 12-10: A/D CONVERSION TIMING



Note1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 12-8: A/D CONVERSION REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
130	TAD	A/D clock period	Standard	1.6	—	—	µs	TOSC based, VREF ≥ 3.0V
			Extended (LC)	2.0	—	—	µs	TOSC based, VREF full range
			Standard	2.0	4.0	6.0	µs	A/D RC Mode
			Extended (LC)	3.0	6.0	9.0	µs	A/D RC Mode
131	TCNV	Conversion time (not including S/H time) **(Note 1)**		11	—	11	TAD	
132	TACQ	Acquisition time		**(Note 2)**	20	—	µs	
				5*	—	—	µs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
134	TGO	Q4 to A/D clock start		—	TOSC/2 §	—	—	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.
135	TSWC	Switching from convert Æ sample time		1.5 §	—	—	TAD	

: * These parameters are characterized but not tested.

: † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

: § This specification ensured by design.

Note 1: ADRES register may be read on the following TCY cycle.

2: See **Section 9.1 "Configuration Bits"** for min. conditions.

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2/99	This is a new data sheet. However, the devices described in this data sheet are the upgrades to the devices found in the *PIC16C6X Data Sheet*, DS30234, and the *PIC16C7X Data Sheet*, DS30390.
B	9/05	Removed Preliminary Status.
C	1/13	Added a note to each package outline drawing.

APPENDIX B: CONVERSION CONSIDERATIONS

There are no previous versions of this device.

APPENDIX C: MIGRATION FROM BASE-LINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: `RETURN, RETFIE, ADDLW`, and `SUBLW`. Two instructions `TRIS` and `OPTION` are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION_REG and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different Reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from Sleep through interrupt is added.
11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. T0CKI pin is also a port pin (RA4) now.
14. FSR is made a full eight-bit register.
15. “In-circuit serial programming” is made possible. The user can program PIC16CXX devices using only five pins: V_{DD}, V_{SS}, $\overline{MCLR}/V_{PP}$, RB6 (clock) and RB7 (data in/out).
16. PCON STATUS register is added with a Power-on Reset Status bit ($\overline{POR}$).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. Brown-out protection circuitry has been added. Controlled by Configuration Word bit BODEN. Brown-out Reset ensures the device is placed in a Reset condition if V_{DD} dips below a fixed setpoint.

To convert code written for PIC16C5X to PIC16CXXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for `CALL`, `GOTO`.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change Reset vector to 0000h.

PIC16C712/716 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-XX	X	/XX	XXX
Device	Frequency Range	Temperature Range	Package	Pattern

Device:	PIC16C712(1), PIC16C712T(2);VDD range 4.0V to 5.5V PIC16LC712(1), PIC16LC712T(2);VDD range 2.5V to 5.5V PIC16C716(1), PIC16C716T(2);VDD range 4.0V to 5.5V PIC16LC716(1), PIC16LC716T(2);VDD range 2.5V to 5.5V	
Frequency Range:	04 = 4 MHz 20 = 20 MHz	
Temperature Range:	blank = 0°C to 70°C I = -40°C to +85°C E = -40°C to +125°C	(Commercial) (Industrial) (Extended)
Package:	JW = Windowed CERDIP SO = SOIC P = PDIP SS = SSOP	
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC16C716 – 04/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.

b) PIC16LC712 – 04I/SO = Industrial temp., SOIC package, 200 kHz, Extended VDD limits.

c) PIC16C712 – 20I/P = Industrial temp., PDIP package, 20MHz, normal VDD limits.

Note 1: C = CMOS
LC = Low Power CMOS

2: T = in tape and reel – SOIC, SSOP packages only.

3: LC extended temperature device is not offered.

4: LC is not offered at 20 MHz

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type (including LC devices).

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Worldwide Site (www.microchip.com)